

MAXWELL SERDES PCIe x2 PERSONALITY CARD

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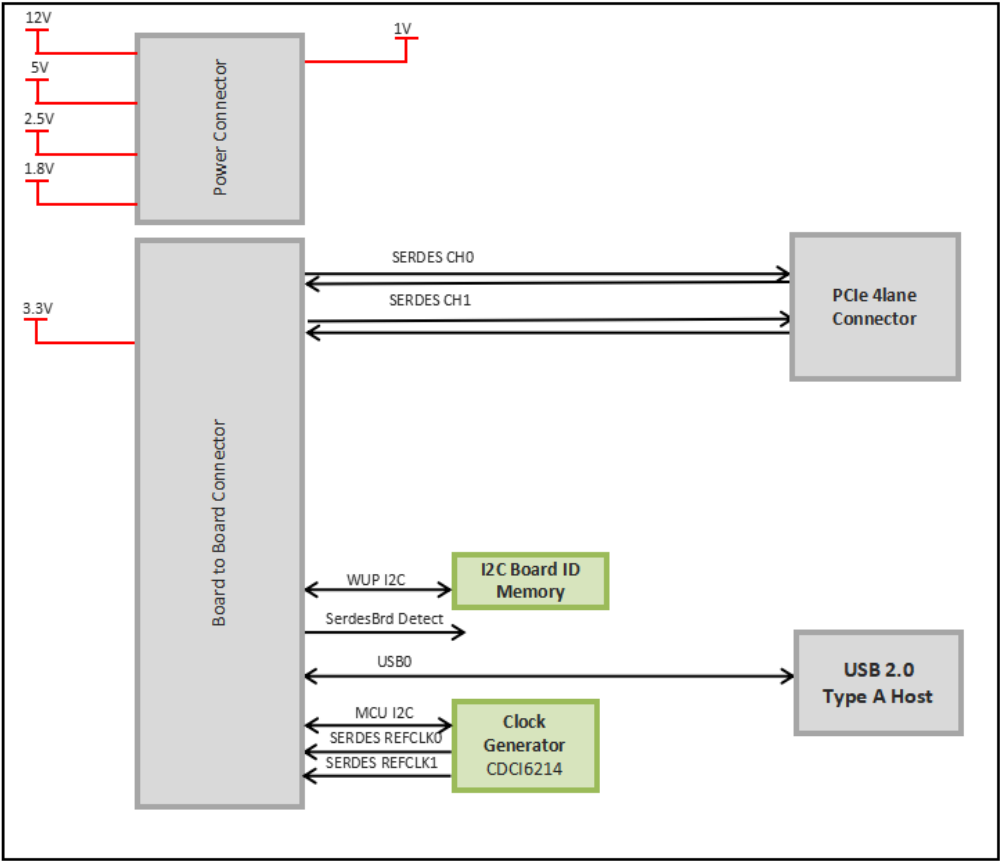
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REV	E3
VER	1.0

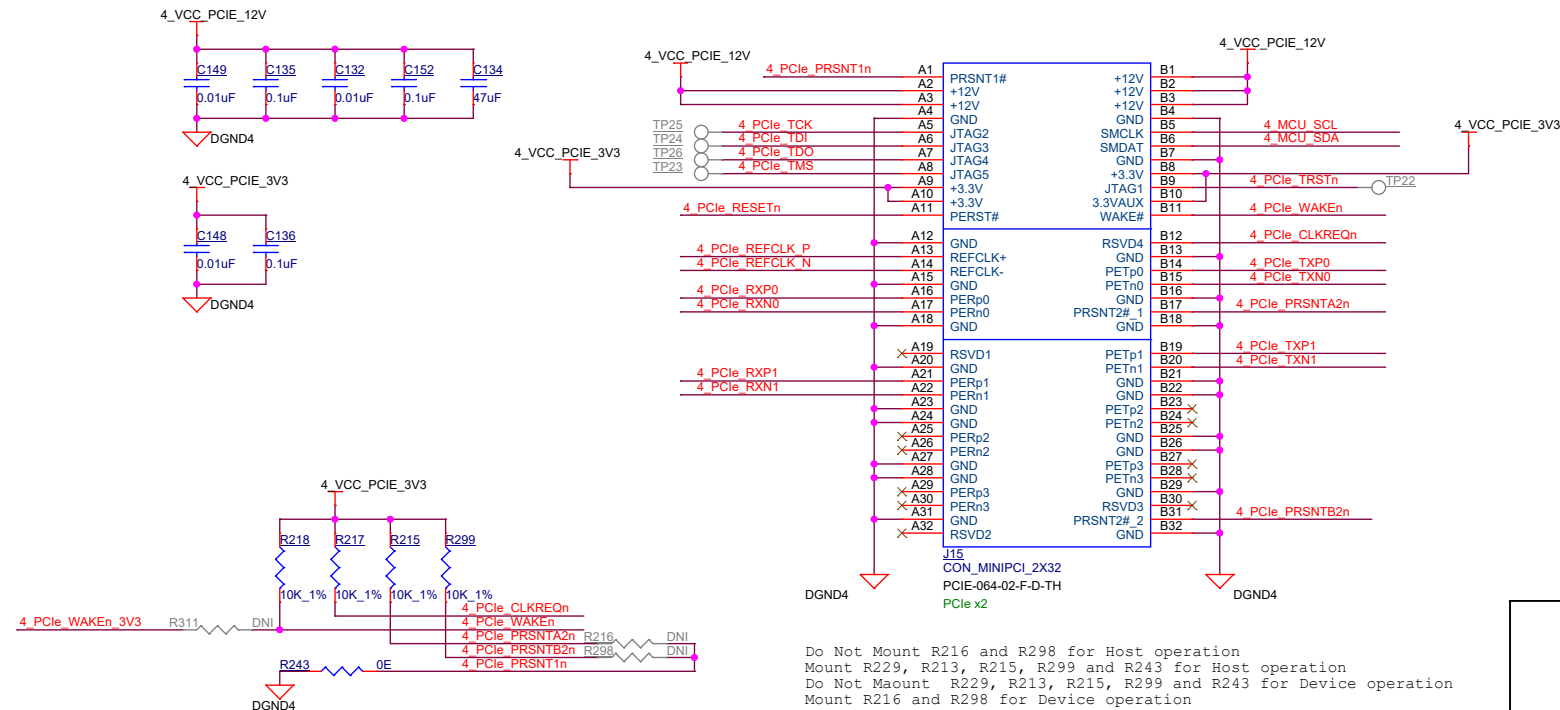
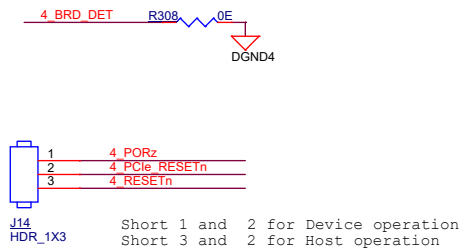
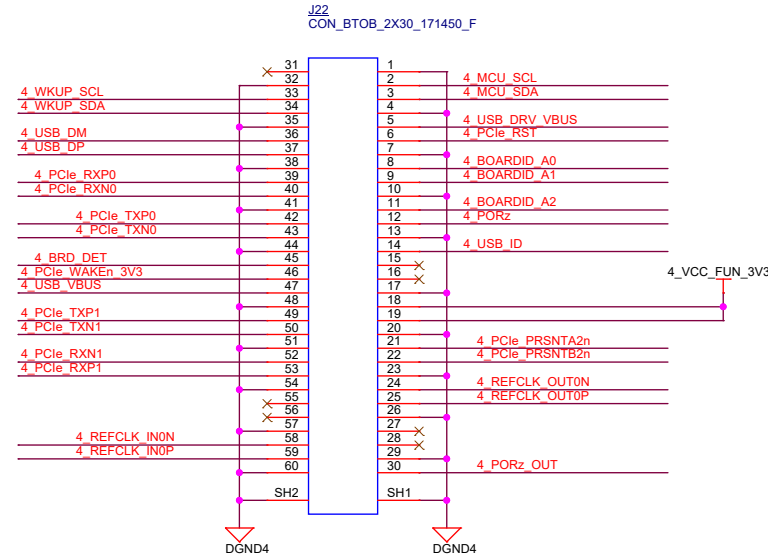
REVISION HISTORY

REV #	VER #	DATE	DESCRIPTION OF CHANGES	AUTHOR	REVIEWED BY	APPROVED BY
E3	0.1	11th JUN 2018	Drafted from Rev E2, Ver 1.0 schematics.	Mistral Design Team	AJIT MB	AJIT MB
E3	0.2	11th JUN 2018	Updated USB 2.0 connector and interface with OTG option.	Mistral Design Team	AJIT MB	AJIT MB
E3	1.0	02nd JULY 2018	Baselined	Mistral Design Team	AJIT MB	AJIT MB

BLOCK DIAGRAM



J22
CON_BTOB_2X30_171450_F



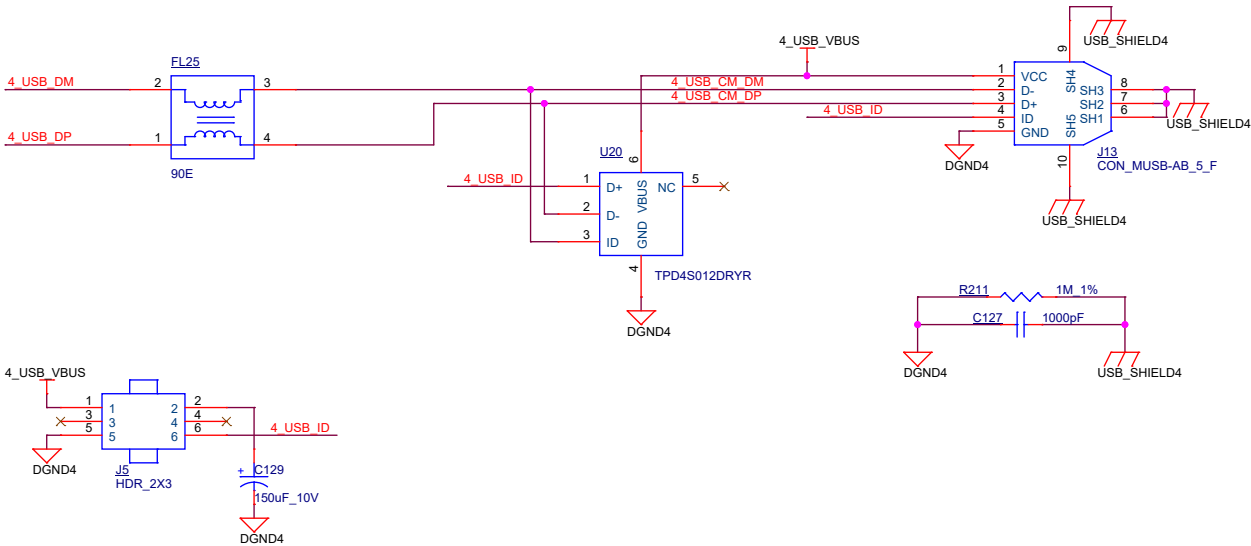
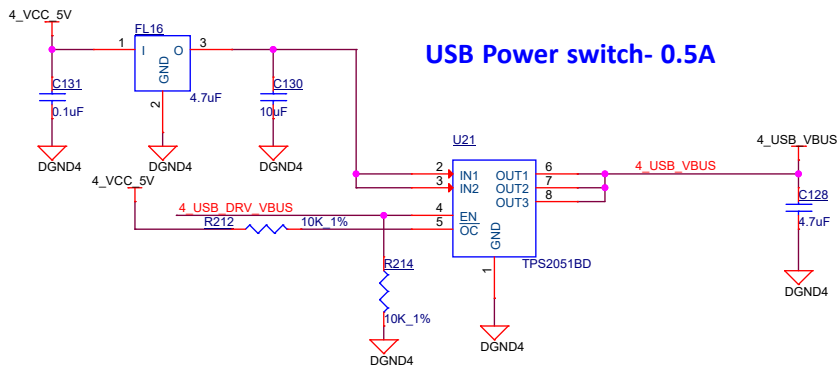
Designed for TI by Mistral Solutions Pvt Ltd



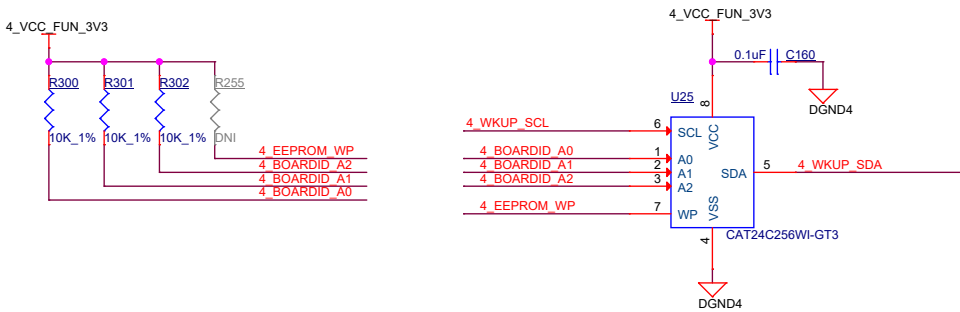
Title			
2LANEPCIe_SERDES & PCIE CON			
Size	PROC067, OP# SER PCIE2LEVM		Rev
C			E3
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USB 2.0

USB 2.0 micro AB Connector



BOARD ID EEPROM



I2C address: 0x54h or Set by host

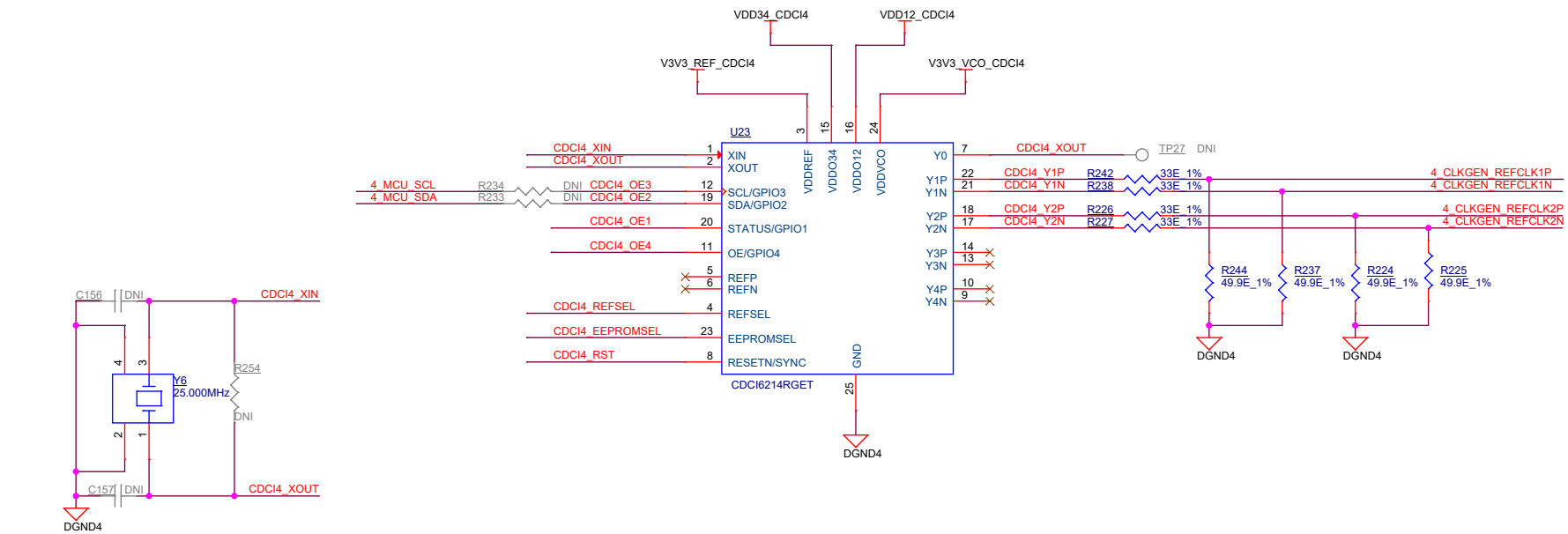
4_BOARDID_A0	4_BOARDID_A0	(25)
4_BOARDID_A1	4_BOARDID_A1	(25)
4_BOARDID_A2	4_BOARDID_A2	(25)
4_USB_ID	4_USB_ID	(25)
4_USB_VBUS	4_USB_VBUS	(25)
4_USB_DRV_VBUS	4_USB_DRV_VBUS	(25)
4_USB_DP	4_USB_DP	(25)
4_USB_DM	4_USB_DM	(25)
4_WKUP_SCL	4_WKUP_SCL	(25)
4_WKUP_SDA	4_WKUP_SDA	(25)

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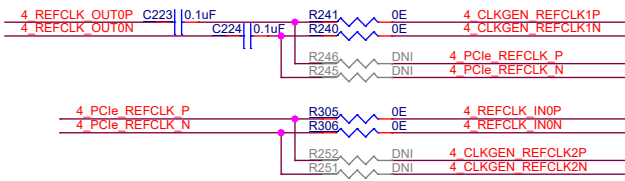
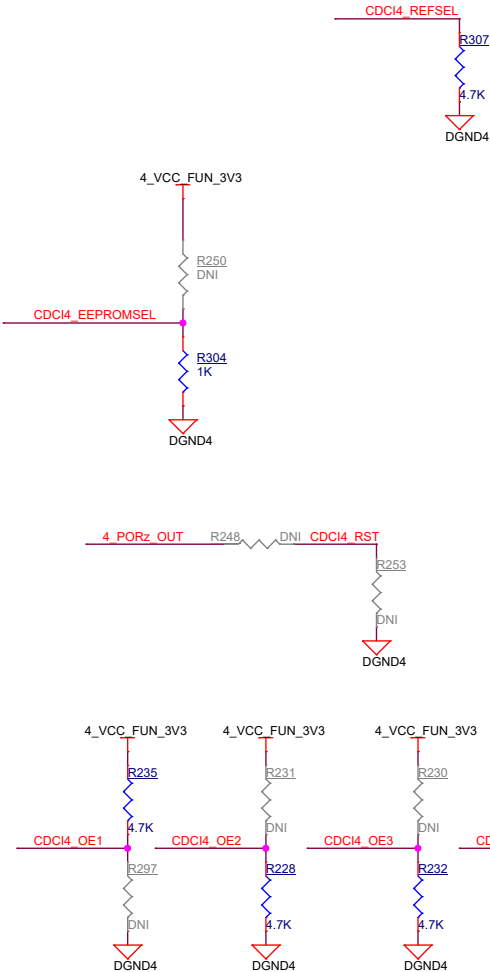


Title		
2LANEPCIE_USB2.0 &BRD_ID		
Size	PROC067, OP# SER PCIE2LEV	Rev
C		E3
Date:	Tuesday, September 04, 2018	Sheet 5 of 7

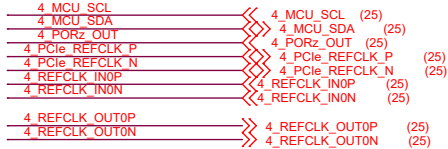
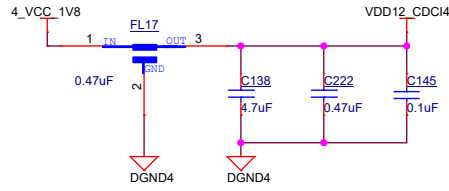
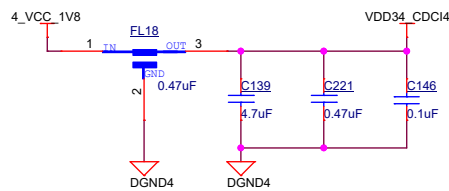
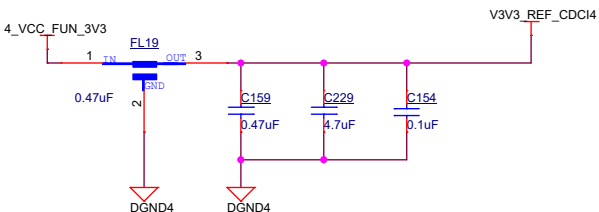
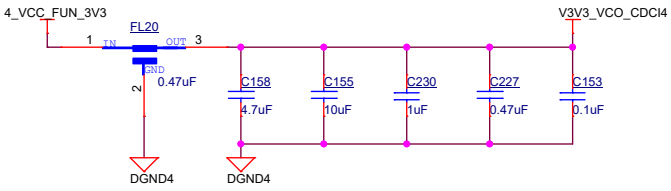
2 Lane PCIe Clock HCSL (100MHz) (EEPROM PAGE 0)



CLOCK ROOT SELECTION



REFCLK_OUTxP	SoC Input Clock
REFCLK_OUTxN	
CLKGEN_REFCLKxP	Output Clock of Clock Generator
CLKGEN_REFCLKxN	
REFCLK_INxP	SoC Output Clock
REFCLK_INxN	
PCle_REFCLKx_P	PCle connector Clock lines
PCle_REFCLKx_N	



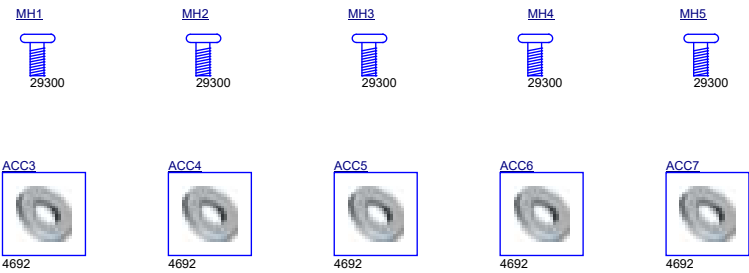
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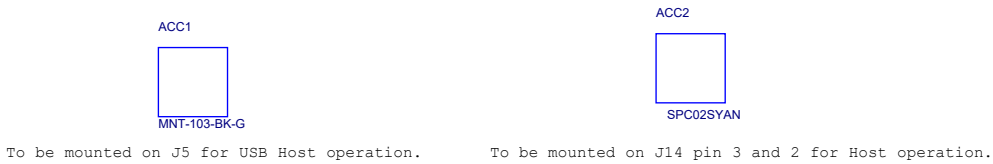
Title 2LANEPCIE_CLK		
Size C	PROC067, OP# SER PCIE2LEV	Rev E3
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HARDWARE SCHEMATICS

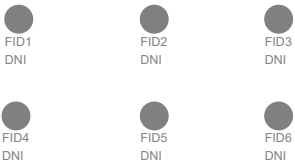
SCREWS and WASHER's



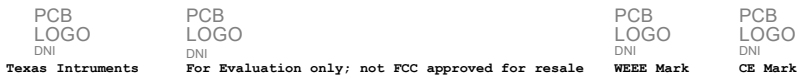
JUMPERs



FIDUCIALS



LOGOs



ASSEMBLY NOTES

1. All MSL components should be baked as per JEDEC standard.
2. PCB should be baked at 120 degree for 8 hours.
3. Board assembly must comply with workmanship standards. IPC-A-610 Class 2, unless otherwise specified.
4. These assemblies are ESD sensitive, ESD precautions shall be observed.
5. These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
6. Provide serial numbers to the assembled boards for identification.
7. The assembled board are wrapped in ESD Covers(individual) and packed securely before shipment.

LABEL

Board Serial No.



BARE PCB



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Title			HARDWARE SCHEMATICS		
Size	PROC067, OP# SER PCIE2LEVIM				Rev
					E3
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